36V Vin Five Channels PMIC for Safety Applications

FEATURES

- Qualified for Automotive Applications
- AEC-Q100 Qualified with the Following Results:
  - Device Temperature Grade 1
- Wide Input Voltage Range: 3.5V-36V
- One Synchronous HV Buck Converter VOUT1:
  - Up to 3A Continuous Output Current
  - Output Voltage of 3.3/3.7/4.6/5V
- Dual Synchronous LV Buck Converters VOUT2, VOUT3:
  - Up to 2A Continuous Output Current
  - Output Voltage Range 0.8V to 2.35V with 50mV Steps
- One Synchronous LV Boost converter VOUT4:
  - Up to 500mA Continuous Output Current
  - Output Voltage of 5V
- One Low-Drop Regulator(LDO) VOUT5:
  - Up to 400mA Continuous Output Current
  - Output Voltage: 1.8/2.7/2.8/2.9/3.3V
- +/- 1.5% Feedback Reference Voltage
- Fixed 2.2MHz Switching Frequency with Integrated Frequency Dither for EMI Mitigation
- FCCM/PFM Selectable
- Programmable Power Sequencer for VOUT2, VOUT3, VOUT4 and VOUT5
- RESETB Output for System Management
- External Clock Synchronization
- Simple/QA Watchdog
- Integrated Protection Features:
  - Hiccup Over Current Protection
  - Output Over-voltage/Under-voltage Protection
  - Adjustable Input Voltage Under-voltage Lockout
  - Thermal Shutdown Protection
- Functional Safety Features:
  - Compliance with IOS26262 Development
  - Hardware Integrity up to Support ASIL-B System
  - ASIL-B Device Certification by TUV
  - BIST
- Up to 1MHz I2C Interface with Optional Packet Error-Checking (PEC)
- Available in QFN-24 (4mm*4mm)

DESCRIPTION

The SCT61451S device is a wide input power management IC with five channels output. The device is designed for MMICs in automotive and industrial radar applications.

The SCT61451S integrates one 3A HV Buck, two identical 2A LV Buck, one 500mA LV Boost and one 400mA LDO. Each channel output is continuously monitored, any over-voltage/under-voltage fault will be detected and the device will enter RESET state. All output voltages are pre-programmed, which saves external feedback divider and minimizes system solution. The switching frequency of HV Buck is 2.2MHz/400kHz selectable. The switching frequency is fixed 2.2MHz for LV buck and boost converters. The device features Frequency Spread Spectrum (FSS) with programmable jittering span of the switching frequency and modulation frequency to reduce the conducted EMI.

The device also integrates simple watchdog mode and QA watchdog mode. The dedicated WDI pin allows trigger pulse generated by MCU. Programmable watchdog window is suitable for a wide variety of applications. The RESETB output can be the sequencer of MCU to protect it from device fault.

The SCT61451S device has protection features such as thermal shutdown, short-circuit protection and over-voltage protection. Disabling all outputs via I2C can reduce the quiescent current to 0.85 mA.

The device has Built-in Self-Test (BIST) Diagnosis over internal analog and digital circuits. All critical comparator and data will be checked during power up stage.

The device is available in a QFN-24(4mm*4mm) Package.

APPLICATIONS

- ADAS
- 77GHz Radar
- Safety MCU

RECOMMENDED OPERATING CONDITIONS

Over operating free-air temperature range unless otherwise noted

PARAMETER	DEFINITION	MIN	MAX	UNIT
V_{IN}	Input voltage range	3.5	36	V
V_{OUT2}	LV Buck2 output voltage range	0.8	2.35	V
V_{OUT3}	LV Buck3 output voltage range	0.8	2.35	V
V_{OUT5}	LDO output voltage range	1.8	3.3	V
T_J	Operating junction temperature	-40	150	°C

ESDRATINGS

PARAMETER	DEFINITION	MIN	MAX	UNIT
V_{ESD}	Human Body Model(HBM), per AEC-Q100-002	-2	+2	kV
	Charged Device Model(CDM), per AEC-Q100-011	-1	+1	kV

THERMAL INFORMATION

PARAMETER	THERMAL METRIC	FCTQFN-24	UNIT
R - $	Junction to ambient thermal resistance(1)	39.68	°C/W
JT	Junction-to-top characterization parameter	1.78	
JB	Junction-to-board characterization parameter(1)	3.26	
R - &(top)	Junction to case (top) thermal resistance(1)	24.67	
R -			

ELECTRICAL CHARACTERISTICS

V_{IN}=12V, T_J=-40°C~150°C, typical values are tested under 25°C.

SYMBOL

ELECTRICAL CHARACTERISTICS (Continued)

V_{IN}=12V, T_J=-40°C~150°C, typical values are tested under 25°C.

SYMBOL	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
R_{DSON_H1}	High-side MOSFET on-resistance	V_{BOOT}-V_{SW}=5V		75	150	m Ÿ
R_{DSON_L1}	Low-side MOSFET on-resistance			50	120	m Ÿ
I_{LIM_HS1}	High-side power MOSFET current limit		4.2	5.2	6.2	A
I_{LIM_LSP1}	Low-side power MOSFET positive current limit		3.2	4.2	5.2	A
I_{LIM_LSN1}	Low-side power MOSFET negative current limit		0.8	2	3.2	A
R_{DIS1}	Discharge resistance	Output disabled		100	200	Ÿ
t_{ON_MIN1}						

esTj EMC /48 62.64 5Tc 0 Tw 4.253 0 T0 0 9.96r

ELECTRICAL CHARACTERISTICS (Continued)

V_{IN}=12V, T_J=-40°C~150°C, typical values are tested under 25°C.

SYMBOL	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
Switching Frequency						
F_{SW}	LV Buck&Boost Switching frequency		1.98	2.2	2.42	MHz
F_{SW1}	HV Buck switching frequency	High frequency option	1.98	2.2	2.42	MHz
		Low frequency option	360	400	440	kHz
F_{FSS_RERIOD}	Frequency spread spectrum period	FSS_PERIOD[0]=0b		4.5		kHz
		FSS_PERIOD[0]=1b		10		kHz
F_{FSS_RANGE}	Frequency spread spectrum in percentage of Fsw	FSS_RANGE[1:0]=00		±5		%
		FSS_RANGE[1:0]=01		±2.5		
		FSS_RANGE[1:0]=10		±7.5		
		FSS_RANGE[1:0]=11		±3.75		
R_{SYNC}	SYNC Input Pulldown	EN high		1.8		M Ÿ
F_{SYNC_RANGE}(1)	SYNC Input Frequency Range	50% duty cycle	1.5		3	MHz
V_{SYN_HI}	Threshold for synchronization	SYNC voltage rising			1.3	V
V_{SYN_LO}		SYNC voltage falling	0.7			
Protection						
$V_{OVUVACC}$	OV/UV accuracy		-1.5		1.5	%
V_{OVTH}	Output over-voltage threshold for all outputs	[redacted]				
		Hysteresis				

ELECTRICAL CHARACTERISTICS (Continued)

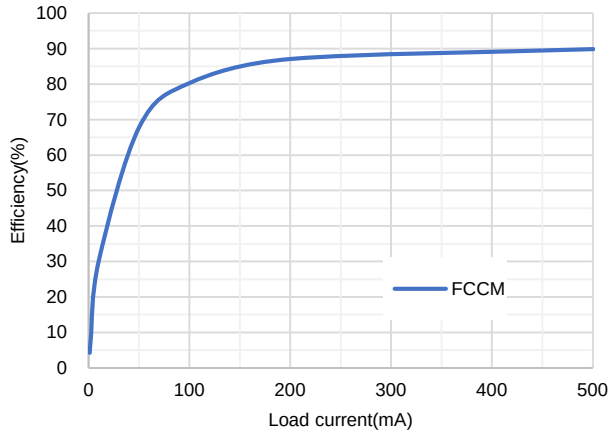
V_{IN}=12V, T_J=-40°C~150°C, typical values are tested under 25°C.

SYMBOL	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
I2C Interface						
V_{IH}	High-level input voltage		1.2			V
V_{IL}	Low-level input voltage				0.4	V
V_{OL}	Low-level output voltage	I_{SINK}=4mA			0.4	V
F_{SCL}(1)	SCL clock frequency				1	MHz
T_{LOW}(1)	Low period of the SCL clock		500			ns
T_{HIGH}(1)	High period of the SCL clock		260			ns
T_{HD_STA}(1)	Hold time (repeated) START condition		260			ns
T_{SU_STA}(1)	Set-up time (repeated) START condition		260			ns
T_{HD_DAT}(1)	Data hold time		0			ns
T_{SU_DAT}(1)	Data set-up time		50			ns
T_R(1)	Rise time of both SCL and SDA signals				120	ns
T_F(1)	Fall time of both SCL and SDA signals				120	ns
T_{SU_STO}(1)	Set-up time for STOP condition		260			ns
C_B(1)	Capacitive load for each bus line				550	pF

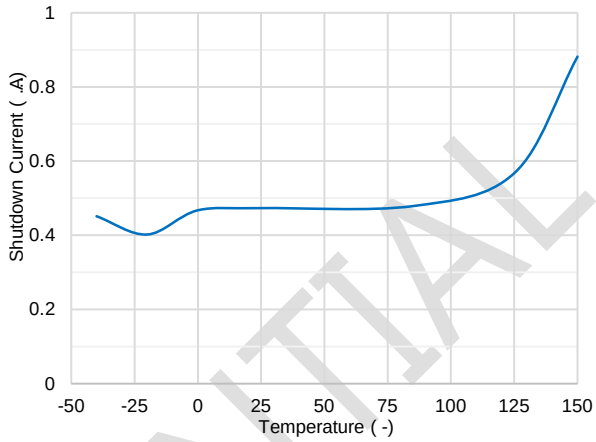
(1) Guaranteed by sample and design characterization, not tested in production.

TYPICAL CHARACTERISTICS (continued)

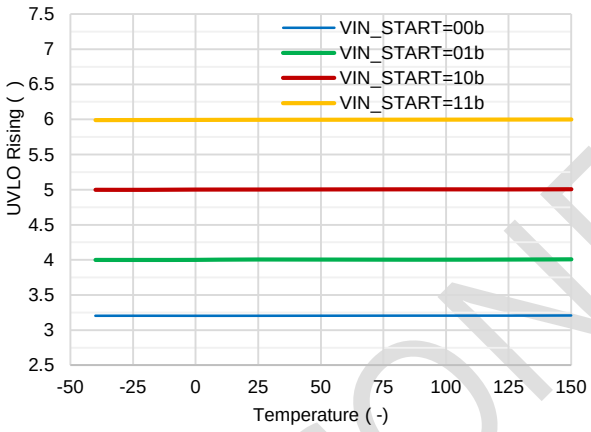
V_{IN}=12V, T_J=-40°C~125°C, unless otherwise noted.



Boost Efficiency vs. Load Current, V_{OUT4}=5V



Shutdown Current vs. Temperature



UVLO Rising Threshold vs. Temperature

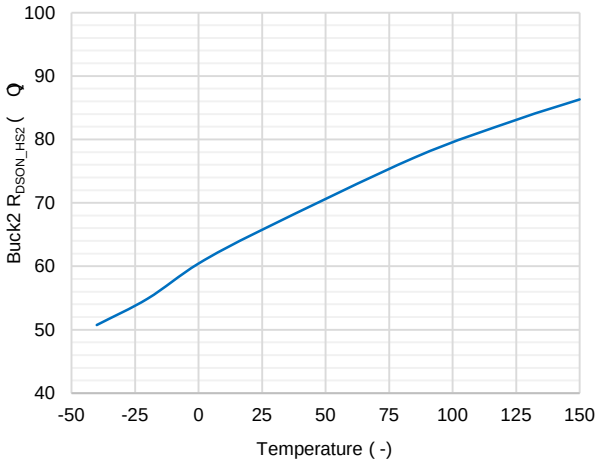
UVLO Falling Threshold vs. Temperature

Buck1 R_{DSON_HS1} vs. Temperature

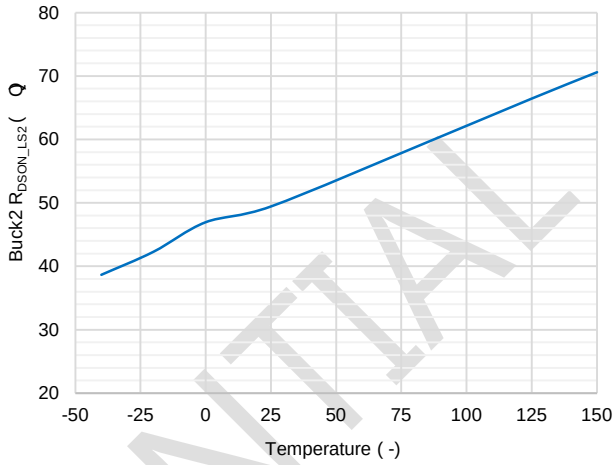
Buck1 R_{DSON_LS1} vs. Temperature

TYPICAL CHARACTERISTICS (continued)

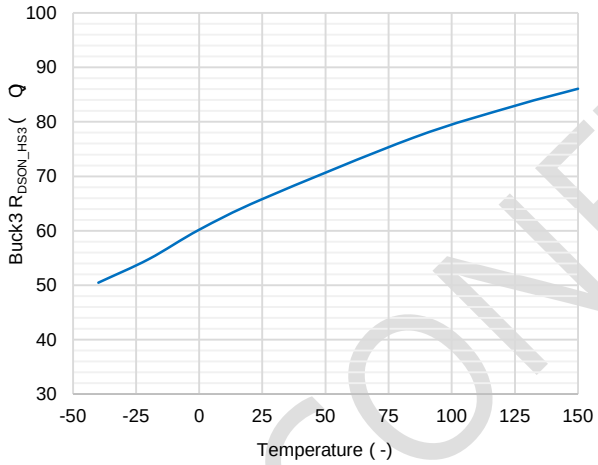
V_{IN}=12V, T_J=-40°C~125°C, unless otherwise noted.



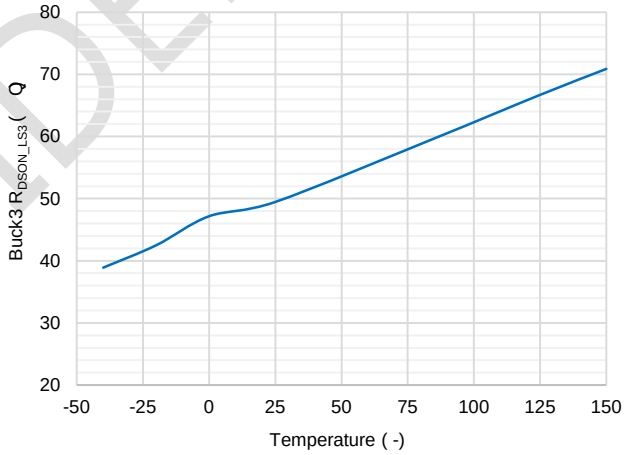
Buck2 R_{DSON_HS2} vs. Temperature



Buck2 R_{DSON_LS2} vs. Temperature



Buck3 R_{DSON_HS3} vs. Temperature



Buck3 R_{DSON_LS3} vs. Temperature

Boost R_{DSON_HS4} vs. Temperature

Boost R_{DSON_LS4} vs. Temperature

FUNCTIONAL BLOCK DIAGRAM

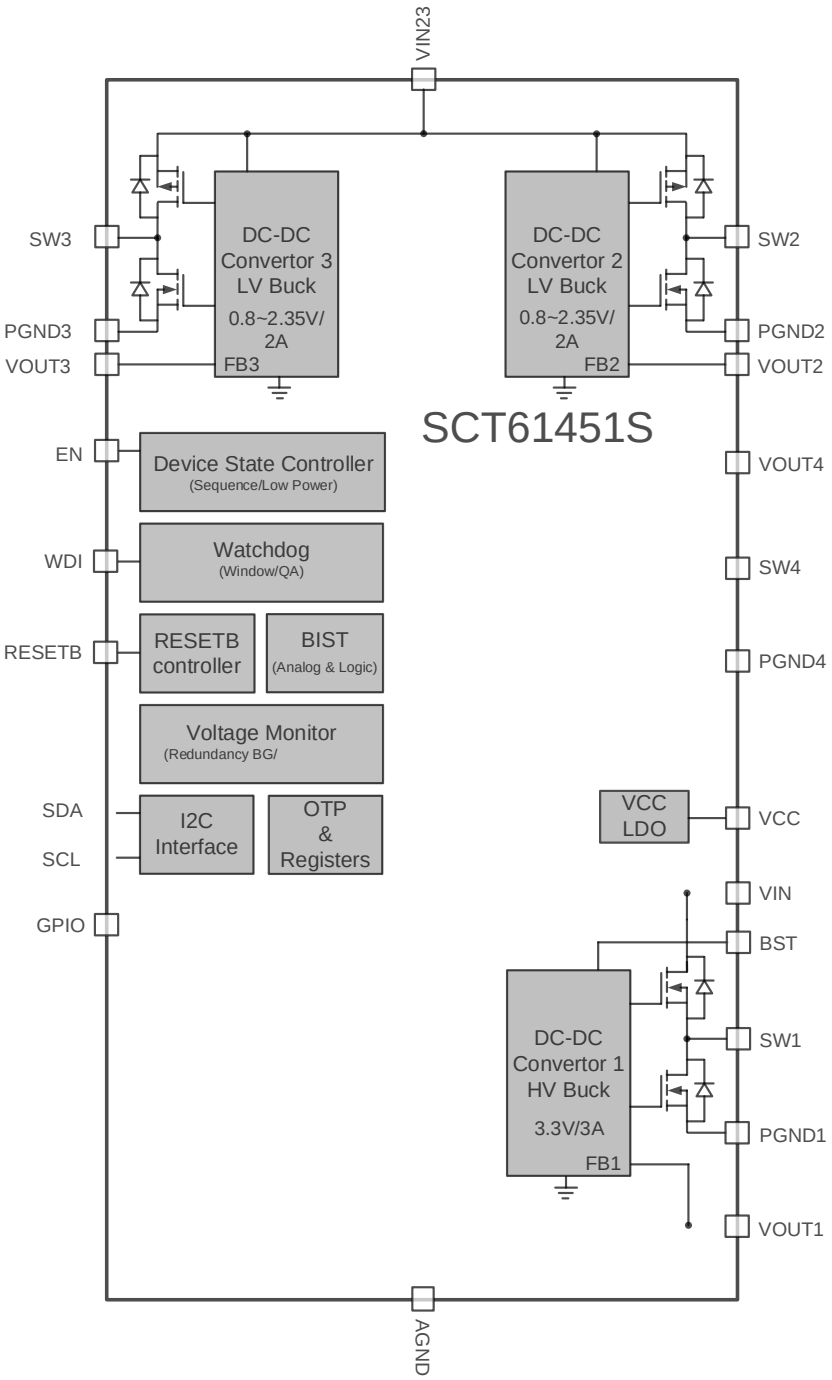


Table 1. State and Function Matrix Table

State	Function											
	I2C	OTP load	Register reset	HV BUCK1	LV BUCK2	LV BUCK3	LV BOOST4	LDO5	Watchdog	OCP	DOVP/DUVP detect	TSD
IDLE	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
LOADOTP	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
LBIST	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
DEEPSAFE	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	ON
ABIST	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	ON
POWERUP	ON	OFF	OFF	UP	UP	UP	UP	UP	OFF	ON	ON	ON
NORMAL	ON	OFF	OFF	ON	ON	ON	ON	ON	ON	ON	ON	ON
RESET	ON	OFF	OFF	ON	ON	ON	ON	ON	OFF	ON	ON	ON

Table 2. State and Functional Pin Metrix Table

State	RESETB
IDLE	Tri-state
LOADOTP	LOW
DEEPSAFE	LOW
ABIST	LOW
POWERUP	LOW
NORMAL	HIGH
RESET	LOW

IDLE State

The device will enter IDLE state whenever VCC is below the UVLO threshold. All functional blocks are disabled and all registers are reset. The device will exit IDLE state and jump to LOADOTP state only when VCC reaches its rising threshold 2.8V.

LOADOTP State

Once the device enters OTPLOAD state, the OTP CRC mechanism will be activated and check through all data. Only when CRC check is passed, the device will load all non-volatile memory to register. And after that, the device will enter LBIST state regardless of CRC check pass or fail. The CRC check result will be recorded in register SYS_STATE.

LBIST State

The diagnostics of the monitoring and protection circuits in the digital core is performed by the LBIST. The LBIST is implemented in this state and check result will be recorded in register SYS_STATE. When LBIST is complete and passed, the device transit to DEEPSAFE state immediately. If failed, the device will stay in LBIST and no functional circuit will be activated. There is a tradeoff between LBIST diagnostic coverage and running time, the LBIST can be disabled by programmed configuration in factory.

DEEPSAFE State

In DEEPSAFE state, all power rails are shut off and indicator pins are pulled low. Regardless of current state, the device will always jump to DEEPSAFE state when any deep safe event occurs. I2C interface and thermal shutdown protection are activated. MCU is able to communicate with device through I2C and read fault register to locate fault.current stal3

- VIN/EN UVLO
- VCC OVP
- VIN OVP
- RESETB Stuck
- Loss of ground

ABIST State

To ensure safety mechanism work well, the device will check through all critical analog comparators before output start-up. If ABIST check is failed, the device will go back to DEEPSAFE state. ABIST will be implemented every time SCT61451S enter ABIST state, the device will transit to POWERUP state once ABIST is passed. Any ABIST failure will be recorded in register SYS_STATE.

POWERUP State

In POWERUP state, all rails will start-up following a dedicated sequence. Since the HV buck VOUT1 is the power supply for the other channels, VOUT1 is always set to start-up first. Then the other channels will rise after turn on delay time respectively. The turn on delay time for each is independent and can be adjusted via changing register CONFIG_PU1 and CONFIG_PU2, thus flexible sequence is available. Deep OV/UV protection is activated to protect channels from destructive OV/UV risk. If all channels finish soft-start and they are within power good range, the RESETB rising timer begins. Once the timer is expired, the device will enter NORMAL state and RESETB will output high. If deep safe event occurs, the state will transit to DEEPSAFE state directly.

NORMAL State

The NORMAL state is the normal running of device with all outputs on. The RESETB pin is released after specific delay time upon entering this state. If watchdog is enabled by register CONFIG_WD3, watchdog window will start after setting delay time. The delay time is configured by WD_1UD[2:0] in register CONFIG_WD3. MCU should feed the watchdog via WDI pin or write answer to specified register periodically. When operating in NOMRAL state, the device will go to RESET state once reset event occurs.

RESET State

All outputs keep on in this state, the device will transit from NORMAL state to RESET state when any of below reset event occurs:

- VOUT1's output is out of OV/UV protection range
- VOUT2's output is out of OV/UV protection range
- VOUT3's output is out of OV/UV protection range
- VOUT4's output is out of OV/UV protection range
- VOUT5's output is out of OV/UV protection range
- Watchdog Failure

When the device enters RESET state, the RESETB pin will assert for a holding time. The device will go back to NORMAL state automatically once the holding time is expired and no reset event, which can be configured in register CONFIG_T1 via I2C. Upon entering NOMRAL state Watchdog failure counter will be reset and start running again. Then MCU should feed the watchdog again.

VIN and EN UVLO

When the VIN pin voltage rises above 3.2V and the EN pin voltage exceeds the enable threshold of 1.2V, the device is enabled. And the device disables when the VIN pin voltage falls below 2.8V or when the EN pin voltage is below 1.0V.

EN pin is connected internally to ground allows the device to be disabled when EN pin is floating to simplify the system design.

High Efficiency Regulators

The switching frequency of HV Buck is 2.2MHz/400kHz selectable. All the LV bucks and boost employ 2.2MHz fixed frequency peak current mode control. Forced continuous conduction mode (FCCM) allows the device to have a high output performance when light load. Built-in UVLO ensures all channels are capable of regulated output under the operating VIN range. Soft-start is fixed at 1ms for all channels. VOUT1 will always be the firstly built rail after power on, the other rails can be configured with range 0ms to 75ms turn on delay. Then the device can achieve a variety of sequence to fit power system.

The VOUT1 is a HV synchronous buck converter directly power from VIN pin. It's regulated at 3.3V with up to 3A continuous current. An external 100nF ceramic bootstrap capacitor between BST and SW1 pin powers high-side power MOSFET gate driver. The bootstrap capacitor voltage is charged from an integrated voltage regulator when high-side power MOSFET is off and low-side power MOSFET is on. Note VOUT1 is the power supply for VOUT2/3/4/5.

The VOUT2 and VOUT3 are two identical LV synchronous buck converter power by VOUT1. Their output can be configured via I2C range from 0.8V to 2.35V with 50mV step. Each is capable of 2A continuous current. To further improve the EMI performance, the VOUT2 and VOUT3 will operate with 180° phase-shifted clock.

The VOUT4 is a LV synchronous boost converter also power by VOUT1. It's regulated at 5V with up to 500mA continuous current.

The VOUT5 is a low-drop regulator(LDO) also powered by VOUT1. The LDO output is factory-programmed at 1.8V, 2.7V, 2.8V, 2.9V or 3.3V with up to 400mA continuous output current.

The converters have proprietary designed gate driver scheme to resist switching node ringing without sacrificing MOSFET turn-on and turn-off time, which further erases high frequency radiation EMI noise caused by the MOSFETs hard switching.

Each output voltage is continuously monitored during operation, the OV/UV threshold can be adjusted independently in register CONFIG_PGSEL1 and CONFIG_PGSEL2.

Deep Over Voltage Protection

If any output exceeds the deep over voltage protection threshold 115%, all outputs will shut off for the hiccup time. When hiccup ends, the normal power up sequence will start again following turn on delay setting in register. When entry hiccup, the output discharge will operate during the hiccup time. The threshold can be configured by bits DEEP_OVP_SEL[1:0] .

Deep Under Voltage Protection

If an output falls below the deep under voltage protection threshold 75%, all outputs will shut off for the hiccup time. When hiccup ends, the normal power up sequence will start again following turn on delay setting in register. When entry hiccup, the output discharge will operate during the hiccup time. The threshold can be configured by bits DEEP_UVP_SEL[1:0] .

Thermal Shutdown

The thermal shutdown protects the device from the damage during excessive heat and power dissipation conditions. Once the junction temperature exceeds 175°C, the internal thermal sensor stops power MOSFETs switching. When the junction temperature falls below 155°C, the device will restart with internal soft start phase.

Over Current Protection (OCP)

The converters implement over current protection with cycle-by-cycle limiting high-side MOSFET peak current and also low-side MOSFET valley current to avoid inductor current running away during unexpected overload and hiccup protection in output hard short condition. When overload or hard short happens, the converter cannot provide output current to satisfy loading requirement even though the inductor current has already been clamped at over current limitation. Thus, output voltage drops below regulated voltage continuously. When peak current point is kicked for continuous 32 times, the converter stops switching, the device will jump to DEEPSAFE state. The hiccup protection mode greatly reduces the average short circuit current to alleviate thermal issues and protect the regulator.

response the watchdog in open window through writing the specific answer to register WD_KEY. A correct watchdog trigger will refresh the whole window cycle immediately and the WD_KEY register being updated. Writing the incorrect answer to the WD_KEY will result in the value written being ignored and a WD_LFSR[0] violation. Writing the correct response during a closed window will result in the write being ignored and a WD_UV[0] violation. If MCU doesn't write byte to WD_KEY and the whole window is expired, WD_EXP[0] violation occurs. LFSR polynomial: x8 + x6 + x5 + x4 + 1. Any violation except WD_LFSR[0] violation will make the WD error counter plus one. When WD error counter reaches the WD_FAIL_CNT[0] (1 or 2 times), a WD Failure is reported and device enters RESET state.

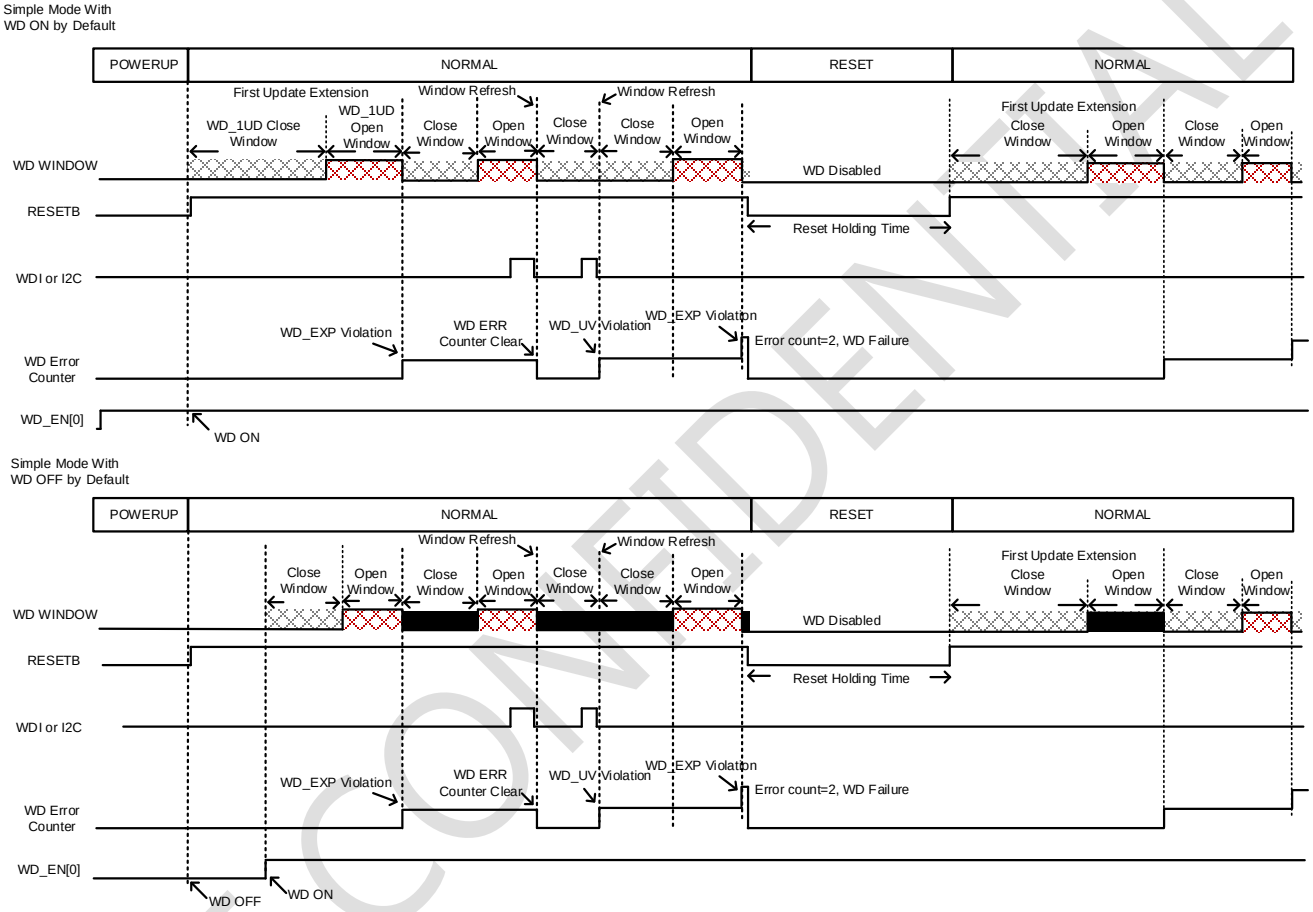


Figure 3a. Simple Watchdog Error Timing

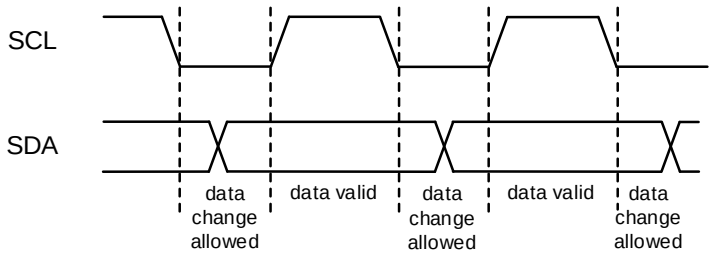


Figure 4. Data Validity Diagram

START and STOP Conditions

The data transfer always generates START and STOP conditions to announce the process. A HIGH to LOW transition on the SDA line while SCL is HIGH defines a START condition. A LOW to HIGH transition on the SDA line while SCL is HIGH defines a STOP condition. Both the START and STOP conditions are generated by master on bus.

The bus is considered to be busy after START condition and released after STOP condition. A repeated START condition during transmission is also valid and will be regard as a new START condition.

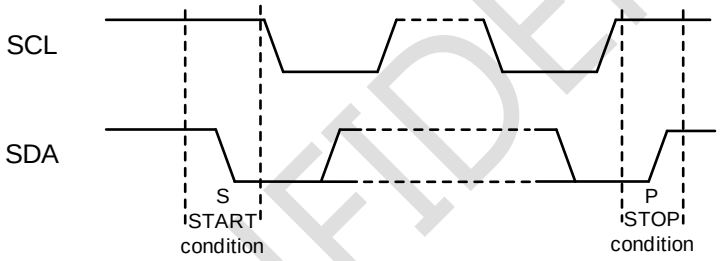


Figure 5. START and STOP Conditions Diagram

Data Transmission

The transferred byte consists of eight bits with the Most Significant Bit (MSB) first. After each byte is transferred, the master will release the SDA line and generate the ninth acknowledge clock pulse on SCL line. The SCT61451S will pull the SDA line LOW during this acknowledge clock, to announce a successful reception and next byte may be sent. If the master is receiver and the last byte is received, it still generates the ninth acknowledge clock pulse but SDA line will not be pulled LOW. It's called not acknowledge signal and indicates the end of transmission.

After the START condition, the master must send a slave address as the first addressing byte. The slave address is seven bits long followed by an eighth R/W bit. The R/W bit defines the data direction. Set the R/W bit to 0 to indicate write command, and a 1 indicates read command. The slave address is factory-programmed between 0x38 through 0x3B, see DEVICE ORDER INFORMATION for details.

Packet Error Checking (PEC)

The SCT61451S supports optional packet error checking (PEC) byte during the I2C communication. PEC can significantly increase fault coverage on the I2C interface. The PEC byte is implemented through CRC-8 polynomial of x8 + x2 + x +1. The PEC byte does not take ACK, NACK, START, STOP, Repeated START bits into calculation. The PEC byte is calculated on the register address and data byte over the entire message from the first START condition, note that the slave address C naalk.1 (w)9e13.2 (i)3n thate (T)-5.5ce (c)5.8 38

- 1 byte of data to register address
- 1 byte of data to the command register
- STOP condition

Read Data Format

A read from the device includes the following:

- Transmission of a START condition
- Slave address with the write bit set to 0
- 1 byte of data to register address
- Restart condition
- Slave address with read bit set to 1
- 1 byte of data to the command register
- STOP condition

Figure 6 illustrates the proper format for one frame.

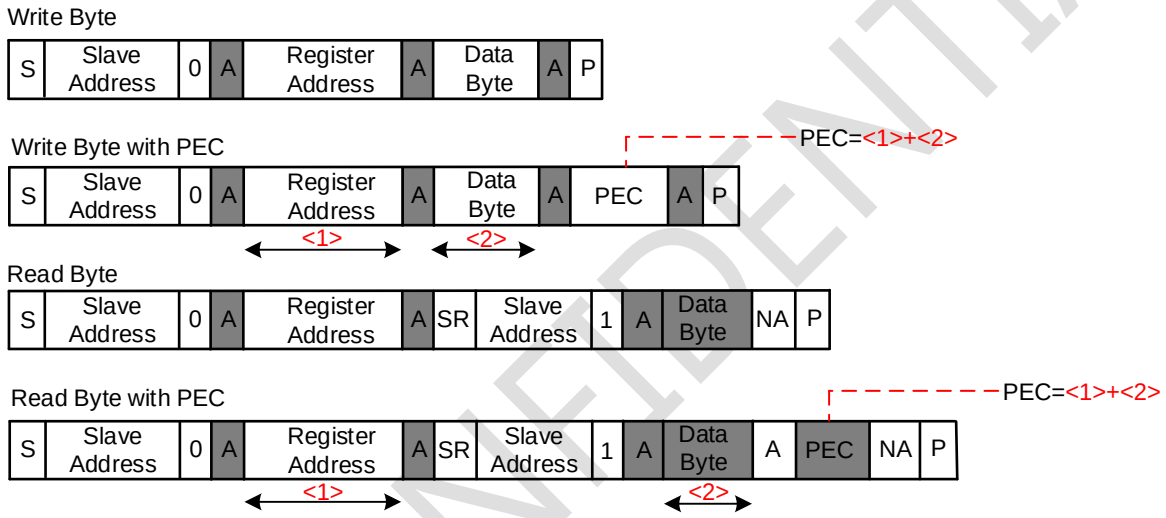


Figure 6. Transmission Data Format Diagram

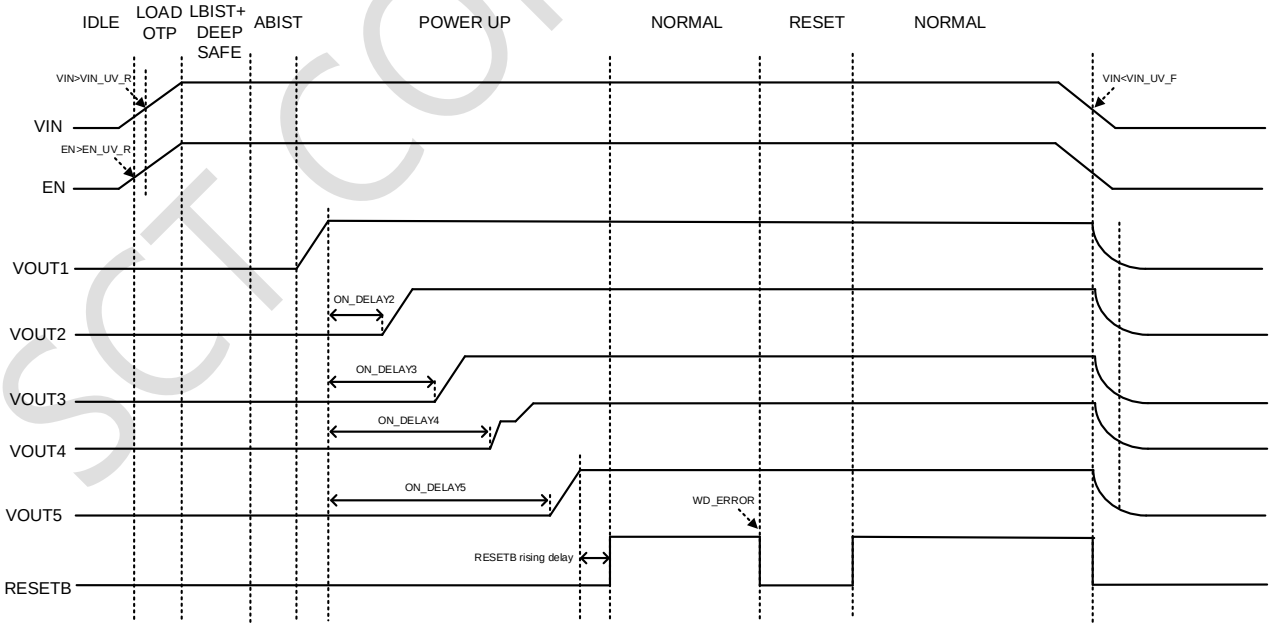


Figure 7. Power on Sequence

Under Voltage Lock-Out

An external voltage divider network of R_1 from the input to EN pin and R_2 from EN pin to the ground can set a higher input voltage's Under Voltage Lock-Out (UVLO) threshold. The UVLO has two thresholds, one for power up when the input voltage is rising and the other for power down or brown outs when the input voltage is falling. Use Equation 1 and Equation 2 to calculate the values of R_1 and R_2 resistors.

- LIR is coefficient of I_{LPP} to I_{OUT}

The total current flowing through the inductor is the inductor ripple current plus the output current. When selecting an inductor, choose its rated current especially the saturation current larger than its peak operation current and RMS current also not be exceeded. Therefore, the peak switching current of inductor, I_{LPEAK} and I_{LRMS} can be calculated as in equation 5 and equation 6.

$$I_{LPEAK} = I_{OUT} + \frac{I_{LPP}}{2} \quad (5)$$

$$I_{LRMS} = \sqrt{I_{OUT}^2 + \frac{1}{12} \times I_{LPP}^2} \quad (6)$$

Where

- I_{LPEAK} is the inductor peak current
- I_{OUT} is the DC load current
- I_{LPP} is the inductor peak-to-peak current
- I_{LRMS} is the inductor RMS current

For a boot converter, the peak-to-peak ripple current in the inductor I_{LPP} can be calculated as

$$I_{LPP\_BOOST} = \frac{1}{L \times \left(\frac{1}{f_{SW}} + \frac{1}{V_{OUT}}\right) \times V_{IN}} \quad (7)$$

Where

- I_{LPP_BOOST} is the

$$I_{CIN\_RMS} = I_{OUT\_MAX} \times \sqrt{\frac{V_{OUT}}{V_{IN}} \times (1 - \frac{V_{OUT}}{V_{IN}})} \quad (10)$$

The worst case condition occurs at $V_{IN}=2*V_{OUT}$, where:

$$I_{CIN\_RMS} = 0.5 \times I_{OUT\_MAX} \quad (11)$$

For simplification, choose an input capacitor with an RMS current rating greater than half of the maximum load current.

When selecting ceramic capacitors, it needs to consider the effective value of a capacitor decreasing as the DC bias voltage across a capacitor increasing.

The input capacitance value determines the input ripple voltage of the regulator. The input voltage ripple can be calculated using Equation 12 and the maximum input voltage ripple occurs at 50% duty cycle.

$$\Delta V_{IN} = \frac{I_{OUT\_MAX}}{F_{SW} \times C_{IN}} \times \frac{V_{OUT}}{V_{IN}} \times (1 - \frac{V_{OUT}}{V_{IN}}) \quad (12)$$

For the boost converter power stage, because of the inductor current ripple, the input voltage changes if there is parasitic inductance and resistance between the power supply and the inductor. It is recommended to have enough input capacitance to make the input voltage ripple less than 100mV. Generally, a 10) input capacitance is recommended for most applications. Choose the right capacitor value carefully by considering high-capacitance ceramic capacitors DC bias effect, which has a strong influence on the final effective capacitance.

Bootstrap Capacitor Selection

$) F H U D P L F F D S D F L W R U connected between the BST pin and SW1 pin for proper operation. A ceramic capacitor with X5R or better grade dielectric is recommended. The capacitor should have a 10V or higher voltage rating.

Output Capacitor Selection

The selection of output capacitor will affect output voltage ripple in steady state and load transient performance.

For buck converter, the output ripple is essentially composed of two parts. One is caused by the inductor current ripple going through the Equivalent Series Resistance ESR of the output capacitors and the other is caused by the inductor current ripple charging and discharging the output capacitors. To achieve small output voltage ripple, choose a low-ESR output capacitor like ceramic capacitor. For ceramic capacitors, the capacitance dominates the output ripple. For simplification, the output voltage ripple can be estimated by Equation 13 desired.

$$\Delta V_{OUT\_BUCK} = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{8 \times L \times F_{SW}^2 \times V_{IN} \times C_{OUT}} \quad (13)$$

Where

- ΔV_{OUT_BUCK} is the output voltage ripple of buck converter
- f_{SW} is the switching frequency
- L is the inductance of inductor
- C_{OUT} is the output capacitance
- V_{OUT} is the output voltage
- V_{IN} is the input voltage

Due to capacitor's degrading under DC bias, the bias voltage can significantly reduce capacitance. Ceramic capacitors can lose most of their capacitance at rated voltage. Therefore, leave margin on the voltage rating to ensure adequate effective capacitance. Typically, two 10) F H U D P L F R X W S X W F D S D F L W R U V Z R U N I

For boost converter, typically, a 22) F H U D P L F R X W S X W F D S D F L W R U V Z R U N I R U P R V W D S S can be used to improve the load transient response. From the required output voltage ripple, use the below equation to calculate the minimum required effective capacitance

$$\Delta V_{OUT\_BOOST} = \frac{(V_{OUT} - V_{IN\_MIN}) \times I_{OUT}}{V_{OUT} \times f_{SW} \times \Delta V_{OUT}} \quad (14)$$

where

- ΔV_{OUT_BOOST} is output voltage ripple caused by charging and discharging of the output capacitor of boost
- V_{IN_MIN} is the minimum input voltage of boost converter.
- V_{OUT} is the output voltage.
- I_{OUT} is the output current.
- f_{SW} is the converter switching frequency.

Table 3. Recommended BOM for Typical Application

Output Rail	Frequency (MHz)	L (uH)	Input Capacitor (uF)	Output Capacitor (uF)
Buck1	2.2	2.2	2 x 10+1 x 0.1	2 x 22
Buck2	2.2	1	10+1 x 0.1	2 x 10
Buck3	2.2	1		2 x 10
Boost4	2.2	1	22	10
LDO5	-	-	-	10
VCC	-	-	-	2.2

Application Waveforms

Vin=12V, V_{OUT1}=3.3V, V_{OUT2}=1.1V, V_{OUT3}=1.5V, V_{OUT4}=5V, V_{OUT5}=2.8V, unless otherwise noted

Figure 10. Power On (Io2=Io3=2A, Io4=0.5A)

Figure 11. Power Off (Io2=Io3=2A, Io4=0.5A)

Figure 12. EN On (Io2=O

Application Waveforms (continued)

Vin=12V, V_{OUT1}=3.3V, V_{OUT2}=1.1V, V_{OUT3}=1.5V, V_{OUT4}=5V, V_{OUT5}=2.8V, unless otherwise noted

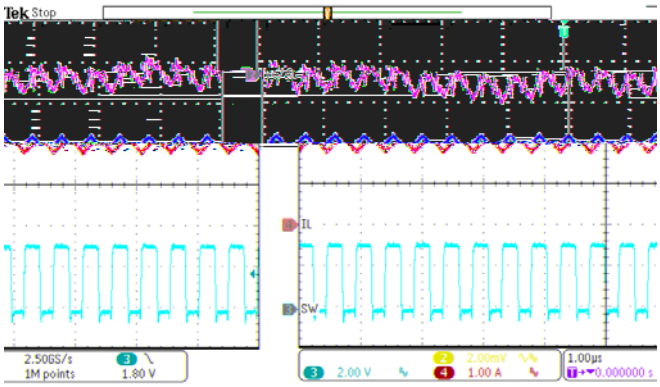


Figure 16. Buck3 Steady State (Io3 = 2A)

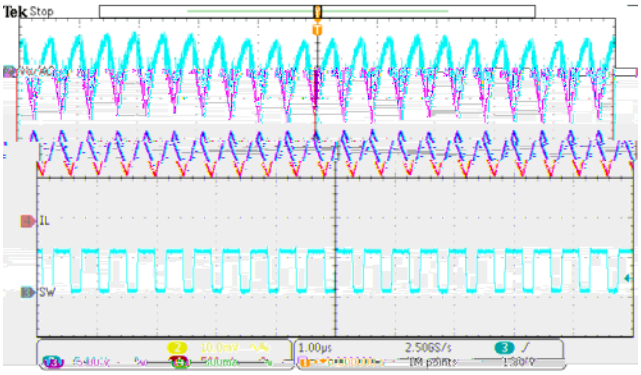
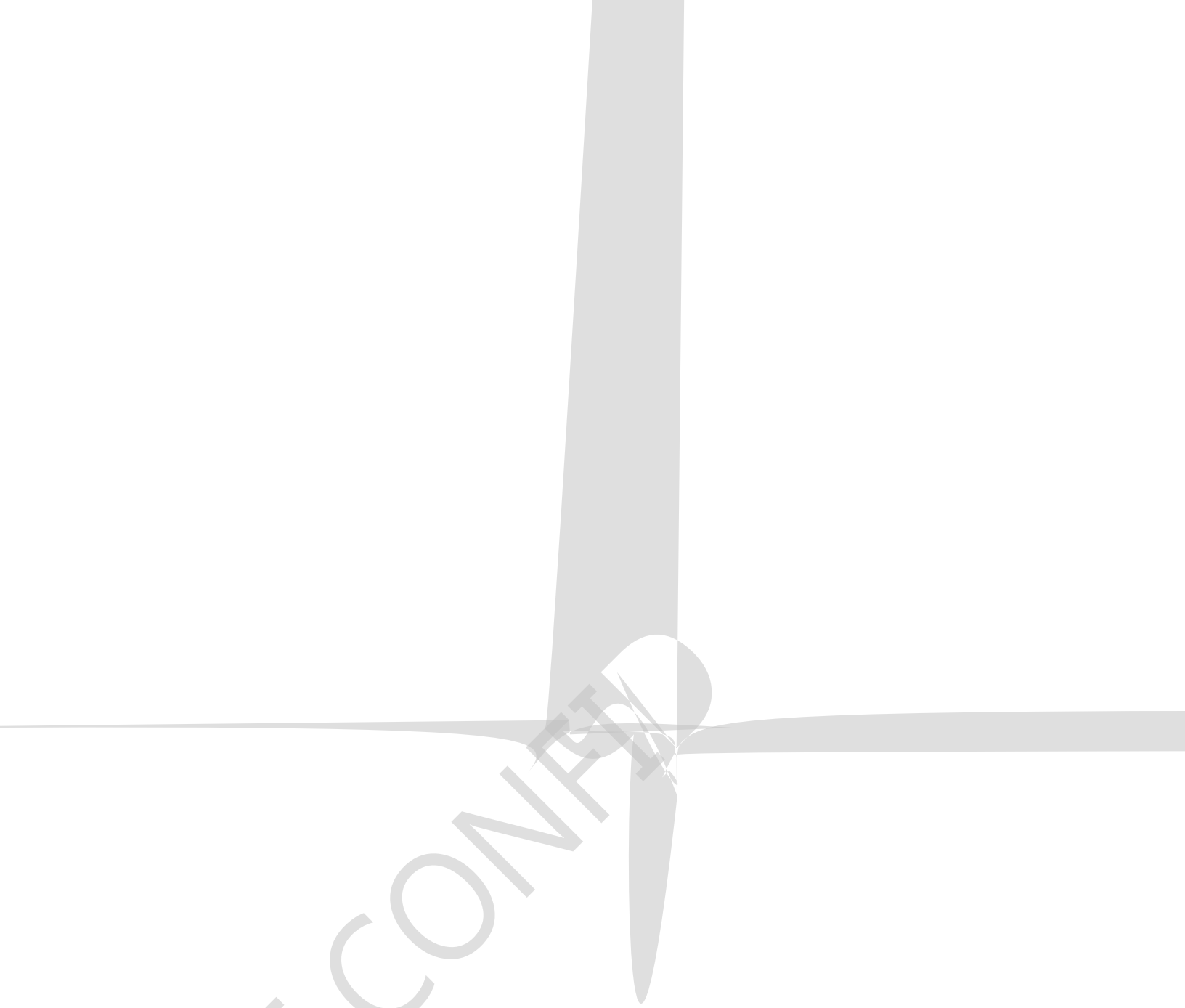


Figure 17. Boost4 Steady State (Io4 = 500mA)



				10: Scale=2.5ms. Delay ranges from 0-37.5ms 11: Scale =5ms. Delay ranges from 0-75ms

CONFIG_T2 [7:0]				
ADDRESS: 0x03				
BITS	FIELD	TYPE	DESCRIPTION	DECODE
[7:6]	RESERVED	R	/	/
[5]	DF_SCALE	W/R	OV/UV Digital Filter. Adds additional filtering to all OV/UV comparators.	Analog Filter Time = 10µs. Added Digital Filter Timeo! =DF[5:0] x 2µs, when DF_SCALE=0, =DF[5:0] x 10µs, when DF_SCALE=1.
[4:0]	DF	W/R		

CONFIG_EN [7:0]				
ADDRESS: 0x05				
BITS	FIELD	TYPE	DESCRIPTION	DECODE
[7:6]	RESERVED	R	/	/
[5]	EN5	W/R	Enable for LDO OUT5. This bit will be activated every time entering DEEPSAFE state, don't change this bit in NORMAL state.	0 = Output Disabled 1 = Output Enabled
[4]	EN4	W/R	Enable for LV BOOST OUT4. This bit will be activated every time entering DEEPSAFE state, don't change this bit in NORMAL state.	0 = Output Disabled 1 = Output Enabled
[3]	EN3	W/R	Enable for LV BUCK OUT3. This bit will be activated every time entering DEEPSAFE state, don't change this bit in NORMAL state.	0 = Output Disabled 1 = Output Enabled
[2]	EN2	W/R	Enable for LV BUCK OUT2. This bit will be activated every time entering DEEPSAFE state, don't change this bit in NORMAL state.	0 = Output Disabled 1 = Output Enabled
[1]	RESERVED	R	/	/
[0]	EN_ALL	W/R	Enable for all channel	0 = Output Disabled 1 = Output Enabled

CONFIG_PU1 [7:0]				
ADDRESS: 0x06				
BITS	FIELD	TYPE	DESCRIPTION	DECODE
[7:4]	ON_DELAY5	W/R	OUT5 Power-Up and Recover Turn On delay.	when DELAY_SCALE=00, t_{ON_DELAY5} = ON_DELAY5[3:0] x 0.5ms when DELAY_SCALE=01, t_{ON_DELAY5} = ON_DELAY5[3:0] x 1ms when DELAY_SCALE=10, t_{ON_DELAY5} = ON_DELAY5[3:0] x 2.5ms when DELAY_SCALE=11, t_{ON_DELAY5} = ON_DELAY5[3:0] x 5ms
[3:0]	ON_DELAY4	W/R	OUT4 Power-Up and Recover Turn On delay.	when DELAY_SCALE=00, t_{ON_DELAY4} = ON_DELAY4[3:0] x 0.5ms when DELAY_SCALE=01, t_{ON_DELAY4} = ON_DELAY4[3:0] x 1ms when DELAY_SCALE=10, t_{ON_DELAY4} =

ON_DELAY4[3:0] x 2.5ms
when DELAY_SCALE=11, t_{ON_DELAY4} = ON_DELAY4[3:0] x 5ms

				1 = WD ERROR is mapped to RESETB pin

STATUV [7:0]				
ADDRESS: 0x0A				
BITS	FIELD	TYPE	DESCRIPTION	DECODE
[7]	UV	Read Clear	UV Comparator Status for all channels with Digital Filter.	0 = All enabled channels are above UV threshold after DF 1 = Any enabled channel is below UV threshold after DF
[6]	RESERVED	R	/	/
[5]	UV_WAR5	Read Clear	UV warning for OUT5, Digital Filter is not included	0 = OUT5 is above UV threshold before DF 1 = OUT5 is below UV threshold before DF
[4]	UV_WAR4	Read Clear	UV warning for OUT4, Digital Filter is not included	0 = OUT4 is above UV threshold before DF 1 = OUT4 is below UV threshold before DF
[3]	UV_WAR3	Read Clear	UV warning for OUT3, Digital Filter is not included	0 = OUT3 is above UV threshold before DF 1 = OUT3 is below UV threshold before DF
[2]	UV_WAR2	Read Clear	UV warning for OUT2, Digital Filter is not included	0 = OUT2 is above UV threshold before DF 1 = OUT2 is below UV threshold before DF
[1]	UV_WAR1	Read Clear	UV warning for OUT1, Digital Filter is not included	0 = OUT1 is above UV threshold before DF 1 = OUT1 is below UV threshold before DF
[0]	RESERVED	R	/	/

STATOV [7:0]				
ADDRESS: 0x0B				
BITS	FIELD	TYPE	DESCRIPTION	DECODE
[7]	OV	Read Clear	OV Comparator Status for all channels with Digital Filter.	0 = All enabled channels are below OV threshold after DF 1 = Any enabled channel is above OV threshold after DF
[6]	RESERVED	R	/	/
[5]	OV_WAR5	Read Clear	OV warning for OUT5	

				1 = OUT3 is above OV threshold before DF
[2]	OV_WAR2	Read Clear	OV warning for OUT2, Digital Filter is not included	0 = OUT2 is below OV threshold before DF 1 = OUT2 is above OV threshold before DF
[1]	OV_WAR1	Read Clear	OV warning for OUT1, Digital Filter is not included	0 = OUT1 is below OV threshold before DF 1 = OUT1 is above OV threshold before DF
[0]	RESERVED	R	/	/

STATOFF [7:0]				
ADDRESS: 0x0C				
BITS	FIELD	TYPE	DESCRIPTION	DECODE
[7:6]	RESERVED	R	/	/
[5]	OFF5	Read Clear	OFF Comparator Status for OUT5	0 = OUT5 is above OFF threshold 1 = OUT5 is below OFF threshold
[4]	OFF4	Read Clear	OFF Comparator Status for OUT4	0 = OUT4 is above OFF threshold 1 = OUT4 is below OFF threshold
[3]	OFF3	Read Clear	OFF Comparator Status for OUT3	0 = OUT3 is above OFF threshold 1 = OUT3 is below OFF threshold
[2]	OFF2	Read Clear	OFF Comparator Status for OUT2	0 = OUT2 is above OFF threshold 1 = OUT2 is below OFF threshold
[1]	OFF1	Read Clear	OFF Comparator Status for OUT1	0 = OUT1 is above OFF threshold 1 = OUT1 is below OFF threshold
[0]	RESERVED	R	/	/

STATD [7:0]				
ADDRESS: 0x0D				
BITS	FIELD	TYPE	DESCRIPTION	DECODE
[7]	RESERVED	R	/	/
[6]	CLK_ERR	Read Clear	CLK fault indicator	0 = No fault detected 1 = CLK error detected
[5]	SUP_ERR	Read Clear	Supply fault indicator, include VCC OV fault and VIN OV fault	0 = No fault detected 1 = VCC OV or VIN OV detected
[4]	RST_ENTER	Read Clear	RESET state indicator	0 = No fault detected 1 = RESET state has entered since the last read.
[3]	DEEPSAFE_ENTER	Read Clear	DEEPSAFE state indicator	0 = No fault detected 1 = DEEPSAFE state has entered since the last read.
[2]	PIN_ERR	Read Clear	Pin fault indicator, include RESETB Pin stuck fault and GND pin LOSS fault	0 = No fault detected 1 = RESETB Short to supply detected or pull-down fail or GND LOSS since the last read
[1]	THSD	Read Clear	Thermal Shutdown Indication	0 = No thermal shutdown 1 = Thermal shutdown has occurred since last read

				11 = Reserved
[5]	RESERVED	R	/	/
[4]	VIN_OVP_EN	W/R	Enable of VIN OVP. When VIN>43V, part enter DEEPSAFE mode.	0 = Disabled 1 = Enabled
[3:2]	VIN_START	W/R	VIN start threshold at VIN rising	00 = 3.2V; 01 = 4V; 10 = 5V; 11 = 6V
[1:0]	VIN_STOP	W/R	VIN stop threshold at VIN falling	00 = 2.8V; 01 = 3.5V; 10 = 4.5V; 11 = 5.5V

CONFIG_PFM [7:0]				
ADDRESS: 0x12				
BITS	FIELD	TYPE	DESCRIPTION	DECODE
[7:4]	RESERVED	R	/	/
[3]	PFM4	W/R	BOOST4 FCCM/PFM mode selection when NORMAL mode.	0 = FCCM 1 = PFM
[2]	PFM3	W/R	BUCK3 FCCM/PFM mode selection when NORMAL mode.	0 = FCCM 1 = PFM
[1]	PFM2	W/R	BUCK2 FCCM/PFM mode selection when NORMAL mode.	0 = FCCM 1 = PFM
[0]	PFM1	W/R	BUCK1 FCCM/PFM mode selection when NORMAL mode.	0 = FCCM 1 = PFM

CONFIG_WD1 [7:0]				
ADDRESS: 0x13				
BITS	FIELD	TYPE	DESCRIPTION	DECODE
[7]	WD_MODE	W/R	Simple Windowed Watchdog Enable	0 = QA watchdog enabled 1 = Simple watchdog enabled
[6]	WD_SCALE	W/R	Watchdog Clock Divider Scale	0 = 128us 1 = 128us*64
[5:0]	WD_CLK	W/R	Watchdog Clock Divider	tWDCLK = (WD0.712.84 Tw 2.0515re f 87

[4]	WD_FAIL_CNT	W/R	Watchdog Failure counter config. When Watchdog failure times reach the counter, report to RESETB and status register.	0 = 1 time 1 = 2 times
[3]	WD_EN	W/R	Watchdog Enable 1 =W1(4])]TJ 0 Tc 0 Tw 1.12 0 Td 1.422 EMC /P <</MCID 1 >>BDC 1U	0 = Disabled 1 = Enabled

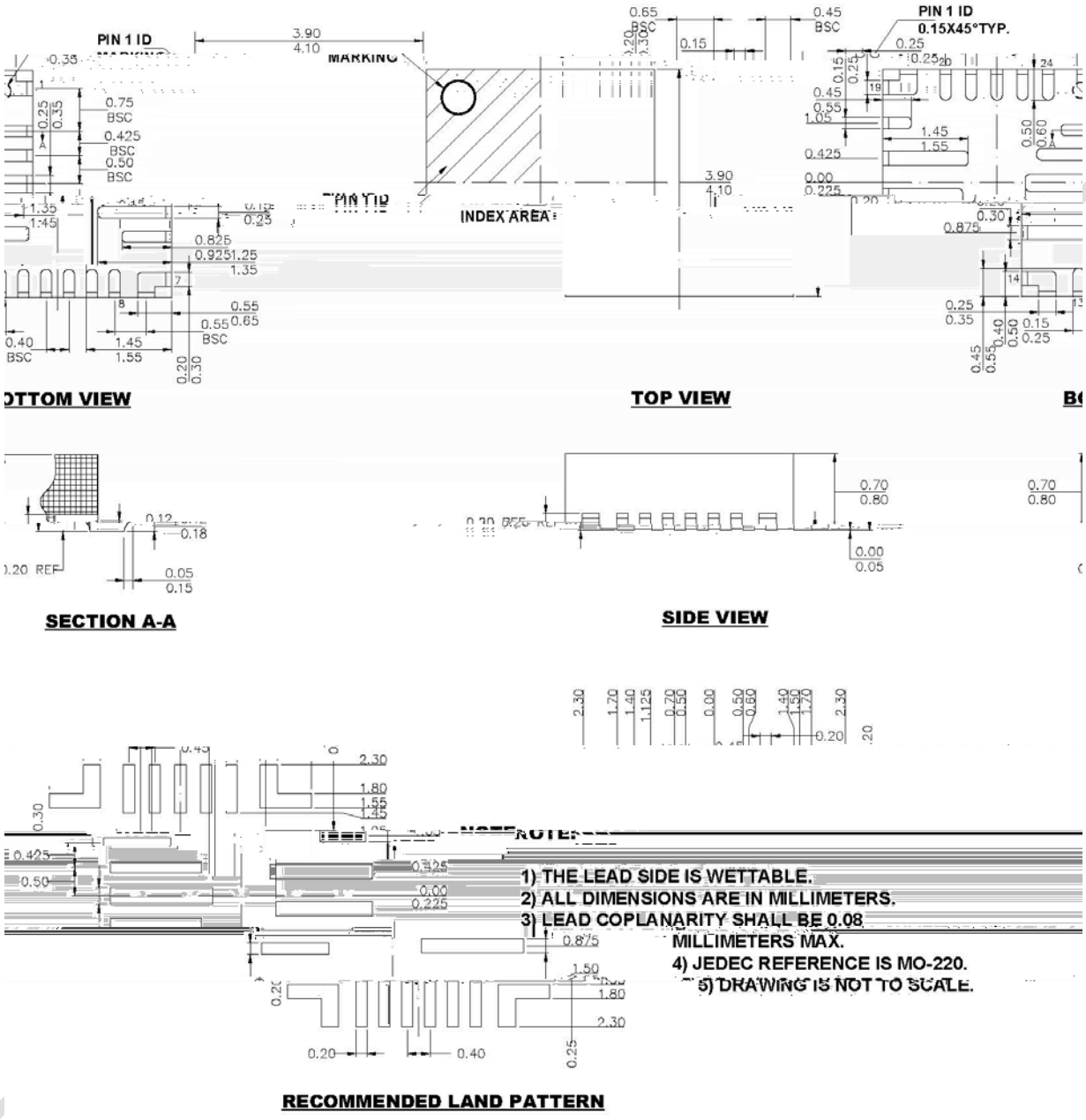
[3:2]	RESERVED	R	/	/
[1:0]	PG5_SEL	W/R	OUT5 OV/UV threshold selection.	00 = Reserved; 01 = ±6%; 10 = ±8%; 11 = ±10%

CONFIG_PGSEL2 [7:0]				
ADDRESS: 0x1A				
BITS	FIELD	TYPE	DESCRIPTION	DECODE
[7:6]	PG4_SEL	W/R	OUT4 OV/UV threshold selection.	00 = Reserved; 01 = ±6%; 10 = ±8%; 11 = ±10%
[5:4]	PG3_SEL	W/R	OUT3 OV/UV threshold selection.	00 = Reserved; 01 = ±6%; 10 = ±8%; 11 = ±10%
[3:2]	PG2_SEL	W/R	OUT2 OV/UV threshold selection.	00 = Reserved; 01 = ±6%; 10 = ±8%; 11 = ±10%
[1:0]	PG1_SEL	W/R	OUT1 OV/UV threshold selection.	00 = Reserved; 01 = ±6%; 10 = ±8%; 11 = ±10%

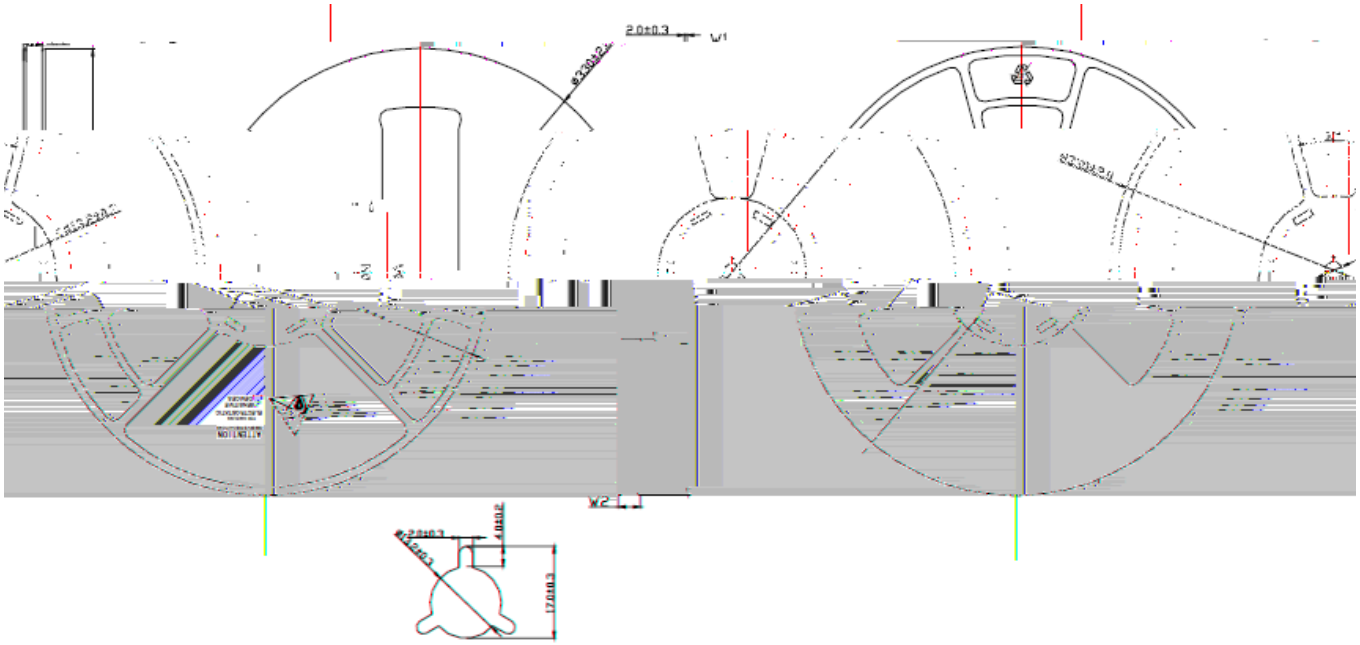
I2C_LOCK [7:0]				
ADDRESS: 0x1C				
BITS	FIELD	TYPE	DESCRIPTION	DECODE
[7:1]	RESERVED	R	/	/
[0]	I2C_LOCK	W/R	Lock Protection. If 0 by default, then this bit can be changed through the I2C.	0 = All registers can be written. 1 = Writes are ignored to protected registers.

SYS_STATE [7:0]				
ADDRESS: 0x22				
BITS	FIELD	TYPE	DESCRIPTION	DECODE
[7]	OTP_CRC_ERR	R	when OTP CRC has error, this bit=1	0 = pass 1 = fail
[6]	ABIST_ERR	R	when ABIST has error, this bit=1	0 = pass 1 = fail
[5]	LBIST_ERR	R	when LBIST has error, this bit=1	0 = pass 1 = fail
[4]	RESERVED	R	/	/
[3:0]	SYS_STATE	R	System state machine.	0000 = IDLE, 0001 = LBIST, 0010 = DEEPSAFE, 0011 = LOADOTP, 0101 = NORMAL, 0110 = ABIST, 0111 = POWERUP, 1101 = RESET, others are reserved

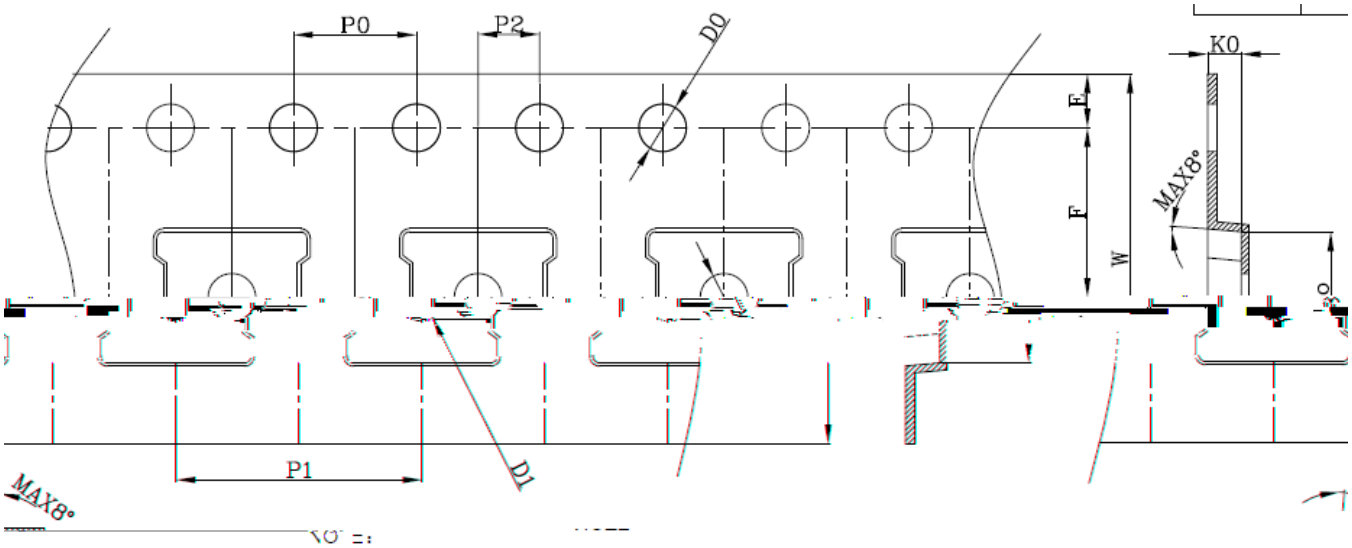
PACKAGE INFORMATION



TAPE AND REEL INFORMATION



PRODUCT SPECIFICATIONS				
TYPE WIDTH	ØA	ØN	W1 (Min)	W2 (Max)
12MM	330±2.0	100±1.0	12.4	19.4
16mm	330±2.0	100±1.0	16.4	23.4
24MM	330±2.0	100±1.0	24.4	31.4
32MM	330±2.0	100±1.0	32.4	39.4
44MM	330±2.0	100±1.0	44.4	51.4



1. 材料：黑色防静电复合PS；
2. 10个链孔的累积公差不能超过0.2mm；
3. 250mm带子的扇形不得超过2mm
4. 所有

SYMBOL	A0	B0	K0	P0	P1	P2	
[illegible]	2.00±0.05	SPEC	[illegible]	[illegible]	[illegible]	[illegible]	[illegible]
D1	W	SYMBOL	T	E	F	D0	
±0.10	12.00±0.30	SPEC	0.30±0.05	1.75±0.10	5.50±0.05	1.55±0.05	1.55

